	CONNECTING CS INDUSTRIES® international and Par	osition Dec PC, Bannockb American co	c laration ourn, Illinois. A opyright conve	All rights reserved un ntions.	nder both	This docume level parts, t	ent is a declarat he declaration e	on of the subst ncompasses al	ances within the lower level mat	manufacture erials for wh	er listed item. iich the manu	Note: if t facturer h	he item is an as as engineering	sembly with lower responsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				eous Materia	als and Mfg Information			
Supplie	r Information													
Company	name*	Company unique ID			1	Unique ID Authority				Response Date*				
nsemi										2023-06-08				
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*			
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item Number KA5H0380RTU		Number Mfr Item Name				Effective Date	Version Manufacturing Site		Weig	ght*	UOM	Unit Type	
			80RTU	FPS FOR DVDP/STB			2023-06-08 CPA			2528	3.3484	mg	Each	
/anufa	cturing Proccess Information	tion												
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		-STD-020 MS	L Rating	Peak Process Body Temperat		berature Max T	ture Max Time at Peak Temp		Number	of Reflow Cyc	les
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30	30 seco		3			
omments	3													
or more	information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	inition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.19	mg	Supplier	Silicon (Si)	7440-21-3		6.19	mg
Die Attach	1.84	mg	Supplier	Silver (Ag)	7440-22-4		0.0276	mg
			А	Lead (Pb)	7439-92-1	7a	1.7204	mg
			Supplier	Tin (Sn)	7440-31-5		0.092	mg
Lead Frame	1545.11	mg	Supplier	Silver (Ag)	7440-22-4		3.1007	mg
			Supplier	Iron (Fe)	7439-89-6		1.5503	mg
			Supplier	Copper (Cu)	7440-50-8		1539.9956	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4633	mg
Mold Compound-Black	953.4	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4- hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		28.6	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		191.0003	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		23.8	mg
			Supplier	Carbon Black (C)	1333-86-4		9.534	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		700.4656	mg
Plating	21.6	mg	Supplier	Tin (Sn)	7440-31-5		21.6	mg
Wire Bond - Cu	0.2084	mg	Supplier	Palladium (Pd)	7440-05-3		0.0042	mg
			Supplier	Copper (Cu)	7440-50-8		0.2042	mg